



Customer Information Notification

201606025I

Issue Date: 26-Jul-2016
Effective Date: 24-Oct-2016

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online



QUALITY

Management Summary

Minor change of carrier tape design for products in SOD323 package.

Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Location	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Process	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input checked="" type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Electrical spec./Test coverage

Introduction of optimized carrier tape for products in SOD323 package

Information Notification

Minor change of carrier tape design for products in SOD323 package.

The design of the area between the pockets of the carrier tape will be changed to optimize the flatness of cover tape along the carrier tape.

There will be no change to any specification or dimensional measures of the carrier tape and the cover tape including no change of peel off force of the cover tape (an illustration of the change is enclosed herewith).

Why do we issue this Information Notification

By modifying the cross bar between the pockets we can ensure a better balanced distance between the components and the cover tape.

This minor modification does not impact the specification of the carrier tape nor the peel off force/behavior of the cover tape.

Identification of Affected Products

Product identification does not change

Impact

no impact to the product's functionality anticipated.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Wali Ahmad
Position Senior Quality Engineer & Customer Support
e-mail address wali.ahmad@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

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NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

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Changed Orderable Part#

BB131,115	BAP65-03,115
BB172X	BAP65-03,115
BB135,115	BAP70-03,115
BA591,115	BAP70-03,115
BAP51-03,115	BB208-03,115
BAP51-03,115	BB208-03,115
BAP64-03,115	BB171X
BAP64-03,115	BB171X
BAP50-03,115	BB172X
BAP63-03,115	BB135,115